SURFACE MOUNT SILICON DUAL, OPPOSING SCHOTTKY DIODE





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKSH-3DO incorporates two (2) galvanically isolated, low V_F silicon diodes with an opposing Anode/Cathode configuration, in a space saving surface mount package, designed for fast switching applications requiring a low forward voltage drop.

MARKING CODE: KDO

FEATURES:

- Dual Opposing (DO) Schottky Diodes
- Small SOT-363 Package

- · Galvanically Isolated
- Low Forward Voltage (0.51V TYP @ 100mA)

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Continuous Forward Current	I _F	100	mA
Power Dissipation	P_{D}	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	ΘιΛ	500	°C/W

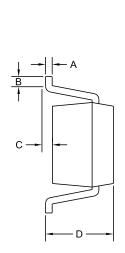
ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

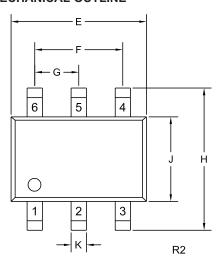
I _R	V _R =25V	MIN	TYP	MAX 500	nA
I_{R}	V _R =25V, T _A =100°C			100	μΑ
BV_R	I _R =100μA	30			V
V_{F}	I _F =2.0mA			0.33	V
V_{F}	I _F =15mA			0.45	V
V_{F}	I _F =100mA		0.51	1.00	V
CJ	V _R =1.0V, f=1.0MHz		7.0		pF
t _{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ Ω			5.0	ns

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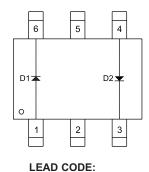


SOT-363 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.004	0.010	0.10	0.25			
В	0.005	-	0.12	-			
С	0.000	0.004	0.00	0.10			
D	0.031	0.043	0.80	1.10			
E	0.071	0.087	1.80	2.20			
F	0.051		1.30				
G	0.026		0.65				
Н	0.075	0.091	1.90	2.30			
J	0.043	0.055	1.10	1.40			
K	0.006	0.012	0.15	0.30			

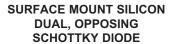
SOT-363 (REV: R2)

1) Anode D1

- 2) NC
- 3) Cathode D2
- 4) Anode D2
- 5) NC
- 6) Cathode D1

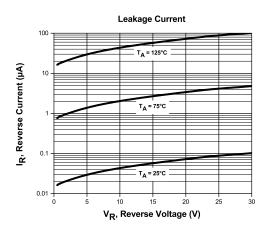
MARKING CODE: KDO

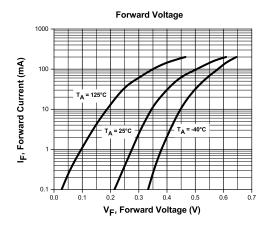
R5 (11-February 2016)

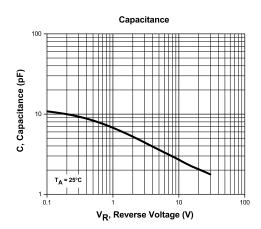


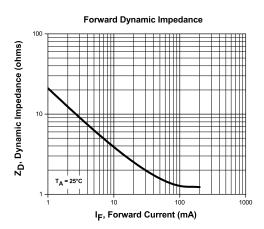


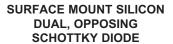
TYPICAL ELECTRICAL CHARACTERISTICS





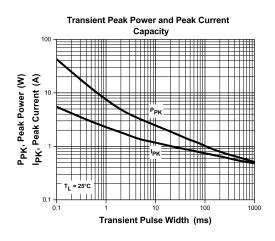


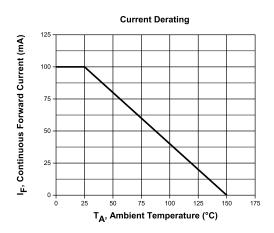


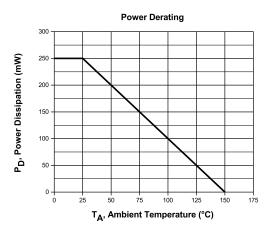




TYPICAL ELECTRICAL CHARACTERISTICS







OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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